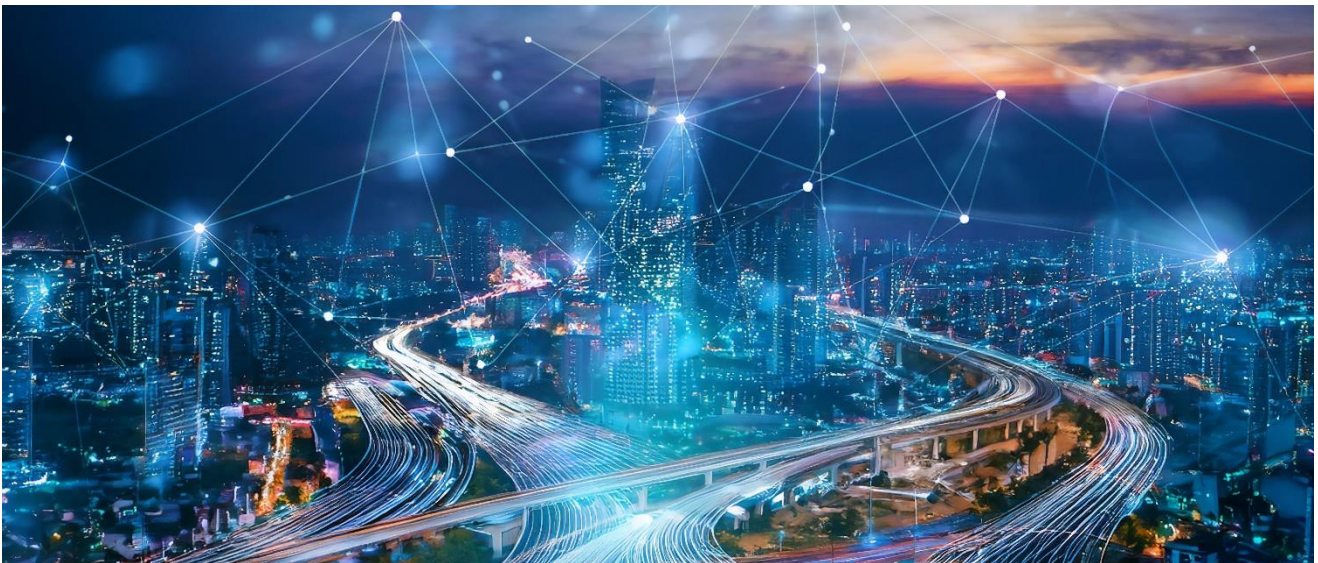


Denka Launches SNECTON, a Low Dielectric Organic Insulating Resin

Denka Company Limited (Headquarters: Chuo-ku, Tokyo; Representative Director and President: Toshio Imai) has launched a low dielectric organic insulating resin (Product name: SNECTON) with the electrical properties (low dielectric constant and low dielectric loss tangent) required of materials to reduce the loss of electrical signals (transmission loss) in next-generation high-speed communications (Beyond 5G and 6G).

The sales of this product have started for copper-clad laminates (CCL) for various high-speed communications equipment. In addition, the adoption of this product for flexible copper-clad laminates (FCCL) and various interlayer insulating materials is now under consideration for its features of remaining soft even after full curing. This product is further expected to find application in a wide range of fields, including PCs, smartphones, data centers, mobile phone base stations, wearable terminals, and automobiles.



SNECTON

The Denka Group has been committed to focusing on the ICT & Energy field in its eight-year Management Plan “Mission 2030,” which covers the fiscal period from 2023 to 2030. In its business efforts, SNECTON will meet the needs of society and our customers as a core material for the telecommunications and energy fields.

Denka Company Limited will continue contributing to people's daily lives and society by applying its world-class chemistry know-how based on the Purpose of Mission 2030: "Make the world a better place as specialists in chemistry."

※SNECTON (word and design) is a registered trademark or trademark of Denka Company Limited.

End of Press Release

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